

In the claims:

Please cancel claims 1- 27, and add the following new claims.

28. An integrated circuit having a field-plated resistor the field-plated resistor comprising:

- a resistor body formed in a substrate, the resistor body having first and second contact regions,
- a first insulating layer on the resistor body, the first insulating layer having a top surface and a bottom surface, with the bottom surface in contact with the resistor body,
- a contact window in the first insulating layer and extending from the top surface of the first insulating layer through the first insulating layer to the resistor body,
- a field plate on the first insulating layer, the field plate having a top surface and a bottom surface, with a portion of the bottom surface extending through the contact window in the first insulating layer and into contact with the first contact region of the resistor,
- a second insulating layer, the second insulating layer at least substantially covering the field plate,
- an electrical contact to the top surface of the field plate,
- an electrical contact to the second contact region of the resistor, and
- metal conductors formed on the second insulating layer.

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cont.

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29. The integrated circuit of claim 28 wherein the field plate comprises polysilicon.

30. The integrated circuit of claim 29 wherein the first and second insulating layers are SiO₂.

31. The integrated circuit of claim 29 wherein the electrical contact to the top surface of the field plate, the electrical contact to the second contact region of the resistor, and the metal conductors formed on the second insulating layer are formed by the same layer.

32. The integrated circuit of claim 29 further comprising an insulative spacer formed around the field plate.

33. The integrated circuit of claim 29 wherein the electrical contact to the top surface of the field plate comprises a barrier layer.

34. The integrated circuit of claim 33 wherein the electrical contact to the second contact region of the resistor comprises a barrier layer.

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REMARKS

Reconsideration of the rejection of the subject matter of this application is requested.

Status of Claims

The number of claims has been reduced substantially. All previously